### CERN 65nm IP blocks

AIDA Final Meeting – WP3.3 9<sup>th</sup> December 2014

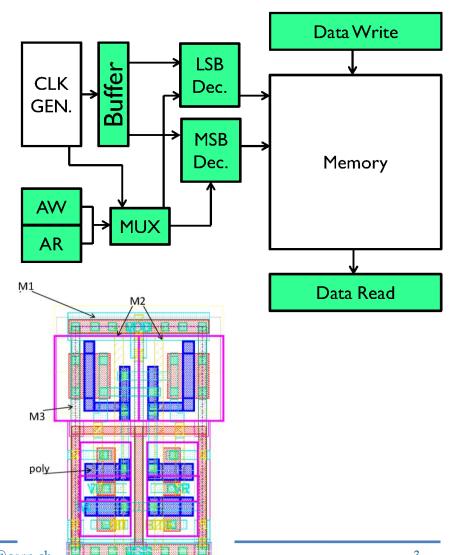
Sandro Bonacini CERN, PH-ESE dept. CH1211, Geneve 23 Switzerland



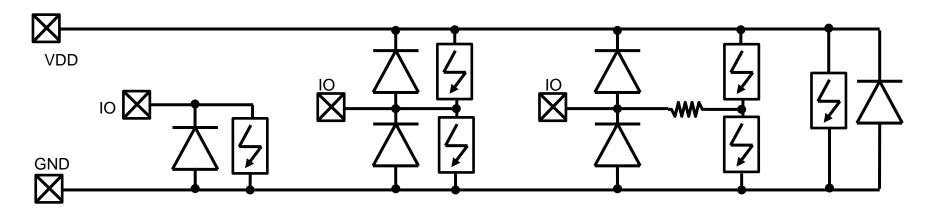
- SRAM compiler
- I/O pad library
- Monitoring ADC
- Bandgaps
- Rad-hard to 200Mrad according to specifications
- Deliverables
  - Schematic (OA)
  - Layout (OA)
  - Abstract (OA)
  - Iib (Liberty) capacitance limits and timing if applicable
  - Verilog / Verilog-AMS models
  - Datasheet



- Pseudo-dual-port (one read + one write in one clock cycle)
- 80 MHz operation
- Minimum size: 128 words of 8 bit
- Max size: 1k words of 256 bits
- Specifications on minimum W of transistors for radiation hardness
  - WPMOS>500nm, WNMOS>200nm
  - Cell size: 1.450 x 2.535 um2
- Part of the blocks are SET tolerant (in green in the figure)
  - If Hamming or other coding is used, SRAM becomes fully SEU tolerant
- Power consumption (simulated for a 1024x32 SRAM)
  - Read+write: 30 uW/MHz
  - Only read: 16 uW/MHz
  - Only write: 17 uW/MHz
  - Idle/static: 3 uW
- Test chip back from fabrication 21/11/2014
  - Silicon & radiation tests will follow
- Presented at AMICSA: <u>https://indico.cern.ch/event/277669/session/5/contribution/12</u>



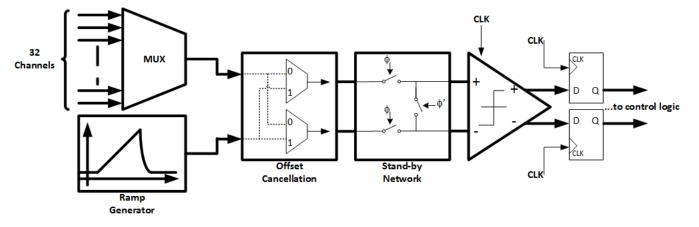
## ESD structures and I/O pads



- Rated for 1.2V
- Only core devices, thin gate oxide
- Outsourced the development work for rad-hard ESD circuitry
  - Power clamps
  - Low-capacitance analog I/O (160 fF, 1 kV HBM ESD)
    - No connection to VDD/DVDD to avoid power supply noise
  - HBM+CDM ESD-protected I/O for digital (200fF, 2 kV ESD)
  - Delivered May 2014
- I/O drivers and receivers designed at CERN
  - Bidirectional digital CMOS I/O cell with slew-rate-controlled output
    - Driving strength control: 16 or 5 mA
    - Enable-controlled pull-up/down resistors (40kohm)



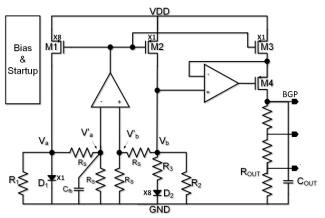
	Parameter		Value	
<ul> <li>ADC</li> <li>Outsourced to Sparkling IC</li> <li>12 bit, 32 channels, single-slope</li> <li>Temperature range -30 C to 80 C</li> <li>Sampling rate 1 kS/s</li> </ul>	# of channels	32		
	Resolution	12 bits		
	Input Range	0V ÷ 800 mV		
	Quantization Error (max)	< 1.5 LSB		
	Noico	Input	Ramp	Comp
power <500uW	Noise <sub>0.1Hz÷1GHz</sub>	117 μV	145 µV	138 µV
<ul> <li>input max slew rate 1 V/s</li> </ul>	Power Consumption (max)	~ 400\\/		
<ul> <li>Wishbone digital interface (commands</li> </ul>	(Analog Only)	≈ 400 µW		
and I/O via registers)	Conversion Time (max)	≈ 430 µs		
Digital logic implemented at CERN	Supply Voltage	$1.2V \pm 10\%$		
Test chip back from fabrication	A rec	0.163 mm <sup>2</sup>		
<ul> <li>Test board design in progress</li> </ul>	Area	(analog part only)		
		(and	ing part of	iiy <i>)</i>



IP Block name:	CERN Bandgap V1 diode		
Parameter		Size	
Dimension		160x520um2	
Bandgap voltage		330mV	
Required supply voltage		1.08-1.32V	
Power consumption		200uW	
Temperature range optimization		-20C +50C	
Max variation (process, T, mismatch, corners)		3.2%	
Min PSRR		-20dB @100KHz	
Capacitor used		Momcap (for compatibility with all possible metal stacks)	
Active element used		Diode between bulk and source of an ELT Pmos (to have gate oxide around the diode instead of STI)	
Designers		Tommaso Vergine, Stefano Michelis	
Status		Back from fabrication, test will follow	
Schedule		Submission in September-October with Pavia/Bergamo and CPPM bandgaps	

# I/O signalsFunctionBGPBandgap outputVDDSupply voltageGNDGround

#### Block Diagram



IP Block name:	CERN Bandgap V2 DTNMOS	
Parame	ter	Size
Dimension		layout to be done
Bandgap voltage		300mV
Required supply voltag	e	1.08-1.32V
Power consumption		50uW
Temperature range opt	timization	-20C +50C
Max variation (process corners)	, T, mismatch,	6-8% (models to be trusted?)
Min PSRR		-30dB @1MHz
Capacitor used		Momcap (for compatibility with all possible metal stacks)
Active element used		DTNMOS (NMOS biased in weak inversion to have the exponential behavior of diode)
Designers		Tommaso Vergine, Stefano Michelis
Status		Back from fabrication, test will follow
Schedule		Submission in September-October with Pavia/Bergamo and CPPM bandgaps

I/O signals	Function
BGP	Bandgap output
VDD	Supply voltage
GND	Ground

## Thank You



## **Backup Slides**



### Foundry provides a wide range of IP blocks

- Electrical fuse blocks / NVM
- PLLs
  - 100MHz 1600MHz
  - Jitter enhancement
- Specialty I/O
  - USB 2.0 / UTMI+
  - DDR2 (up to 800Mpbs), DDR1 (up to 533 Mbps)
  - Crystal oscillator, 32kHz
- ROM compiler
- Register File compiler
  - Single- and dual-port
- SRAM compiler
  - Single-port and dual-port
  - Low-power and low-leakage

#### Not made / not tested for radiation performance



#### I2C slave

- 7- and 10-bit addressing
- HDLC communication protocol
  - Variable bit-rate
  - Average 7% bandwidth overhead
- 7b8b communication protocol
  - DC balanced
  - Fixed latency
  - Control characters available